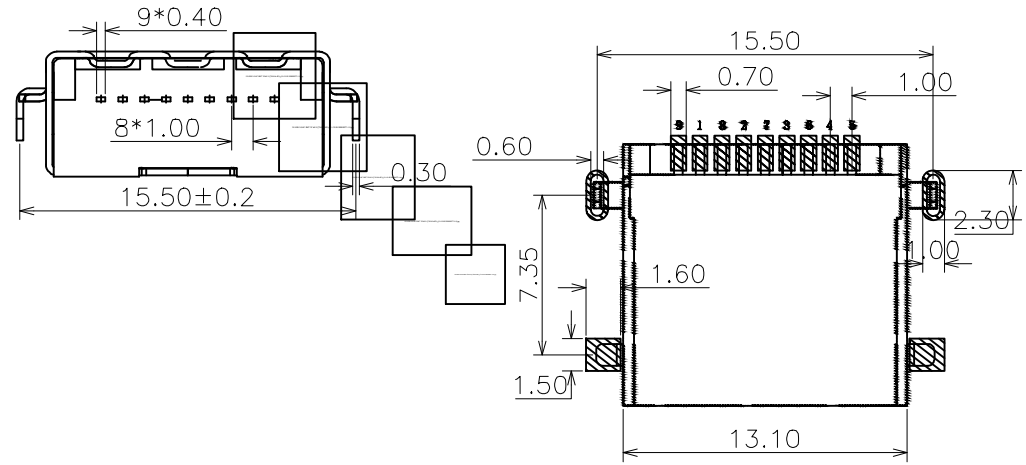
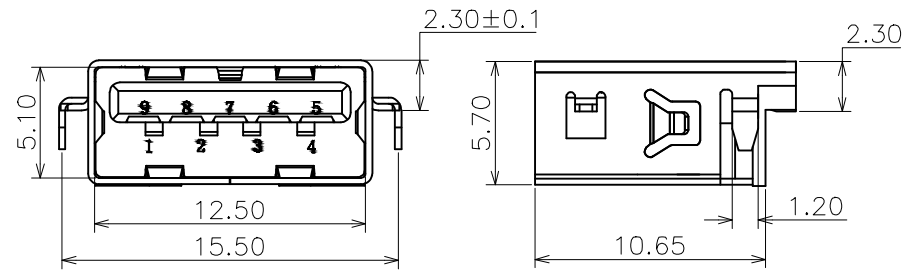


All raw material,production process,electroplating must meet the requirements of EU RoHS.

REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A0			RELEASE TO CUSTOMER	230201	HANG

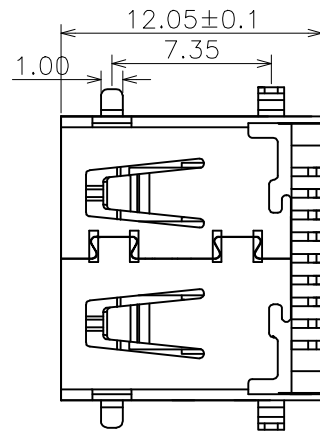
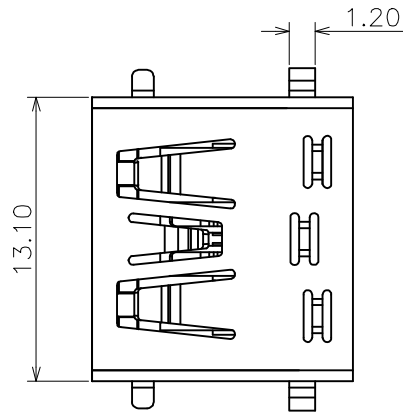


PCB Layout

MATERIAL:

- 1.CONTACT: BRONZE
- 2.SHELL: SUS & SPCC
- 3.INSULATOR: HIGH TEMPERATURE PLASTIC

1. CONTACT RESISTANCE: 30mΩ MAXIMUM
2. CURRENT RATING: 1.5A
3. DIELECTRIC WITHSTANDING VOLTAGE: 100V AC R.M.S.
4. INSULATION RESISTANCE 100MEGOHMS MIN
5. OPERATING TEMPERATURE: -40°C ~ 85°C
6. MATING FORCE: 3.57kgf MAX
7. UNMATED FORCE: 0.82kgf MIN AFTER TEST
8. DURABILITY MANDATORY: 1500 CYCLES



Pin	Singnal Name	
1	VBUS	USB2.0 Contact Pin
2	D-	
3	D+	
4	GND	
5	StdA_SSRX-	USB3.0 Contact Pin
6	StdA_SSRX+	
7	GND_DRAIN	
8	StdA_SSTX-	
9	StdA_SSTX+	

深圳朗思达科技有限公司

DRAW NO.	DATE	DRAW NAME: 15 USB 3.0 AF SMT 沉板2.3 前贴后插 平口 L12.05	
DESIGN HANG	20200218	P/N NO. 20900077	CIB CODE:
CHECK ZHAOZZ	20200218	UNIT: mm	MODEL:
APPROVED RYAN	20200218	SHEET: N/A	REV. A0 SCALE N/A

DIM	TOL	DIM	TOL
X.	±0.30	X'	±4.0'
X.X	±0.25	X.X'	±3.0'
X.XX	±0.20	X.XX'	±2.0'
X.XXX	±0.10	X.XXX'	±1.0'

THIS DRAWING CONTAINS INFORMATION THAT IS PROVIDED BY DONGSHI
OR ELECTRONIC EQUIPMENT AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION